

# 2SD1330

## Silicon NPN epitaxial planar type

For low-voltage output amplification

For muting

For DC-DC converter

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Low ON resistance  $R_{on}$
- High forward current transfer ratio  $h_{FE}$
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

| Parameter                             | Symbol    | Rating      | Unit       |
|---------------------------------------|-----------|-------------|------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | 25          | V          |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | 20          | V          |
| Emitter-base voltage (Collector open) | $V_{EBO}$ | 12          | V          |
| Collector current                     | $I_C$     | 0.5         | A          |
| Peak collector current                | $I_{CP}$  | 1           | A          |
| Collector power dissipation           | $P_C$     | 600         | mW         |
| Junction temperature                  | $T_j$     | 150         | $^\circ C$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ C$ |

### ■ Electrical Characteristics $T_a = 25^\circ C \pm 3^\circ C$

| Parameter  | Symbol        | Conditions                                 | Min | Typ  | Max | Unit     |
|--|---------------|--|-----|------|-----|----------|
| Collector-base voltage (Emitter open)                            | $V_{CBO}$     | $I_C = 10 \mu A, I_E = 0$                  | 25  |      |     | V        |
| Collector-emitter voltage (Base open)                            | $V_{CEO}$     | $I_C = 1 mA, I_B = 0$                      | 20  |      |     | V        |
| Emitter-base voltage (Collector open)                            | $V_{EBO}$     | $I_E = 10 \mu A, I_C = 0$                  | 12  |      |     | V        |
| Collector-base cutoff current (Emitter open)                     | $I_{CBO}$     | $V_{CB} = 25 V, I_E = 0$                   |     |      | 100 | nA       |
| Forward current transfer ratio *1                                | $h_{FE1}$ *2  | $V_{CE} = 2 V, I_C = 0.5 A$                | 200 |      | 800 | —        |
|  |               | $V_{CE} = 2 V, I_C = 1 A$                  | 60  |      |     |          |
| Collector-emitter saturation voltage                             | $V_{CE(sat)}$ | $I_C = 0.5 A, I_B = 20 mA$                 |     | 0.13 | 0.4 | V        |
| Base-emitter saturation voltage                                  | $V_{BE(sat)}$ | $I_C = 0.5 A, I_B = 50 mA$                 |     |      | 1.2 | V        |
| Transition frequency   | $f_T$         | $V_{CB} = 10 V, I_E = -50 mA, f = 200 MHz$ |     | 200  |     | MHz      |
| Collector output capacitance (Common base, input open circuited) | $C_{ob}$      | $V_{CB} = 10 V, I_E = 0, f = 1 MHz$        |     | 10   |     | pF       |
| ON resistance *3   | $R_{on}$      |  |     | 1    |     | $\Omega$ |

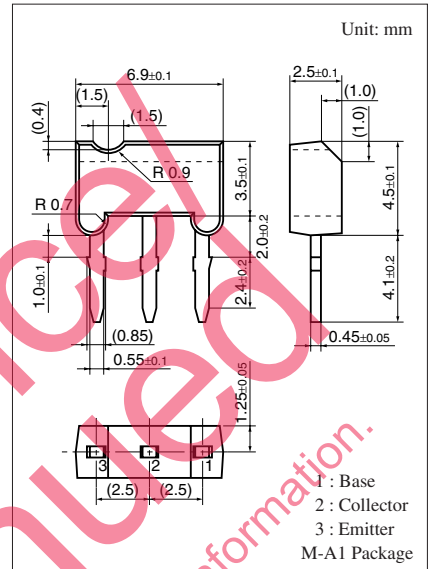
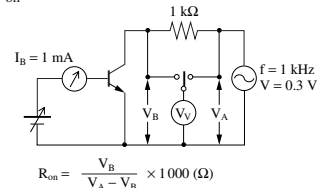
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

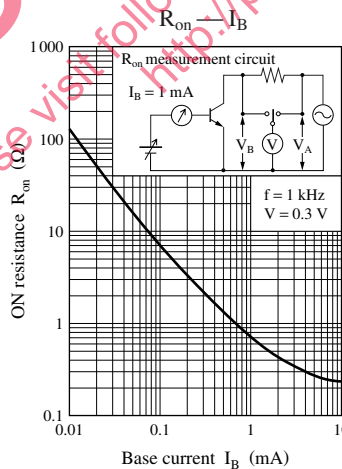
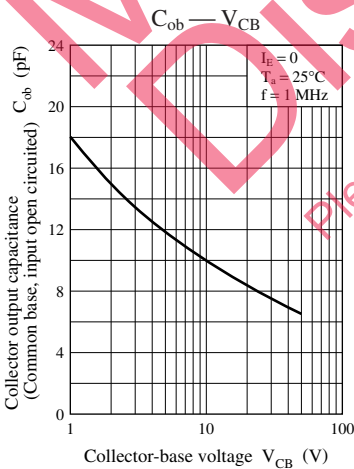
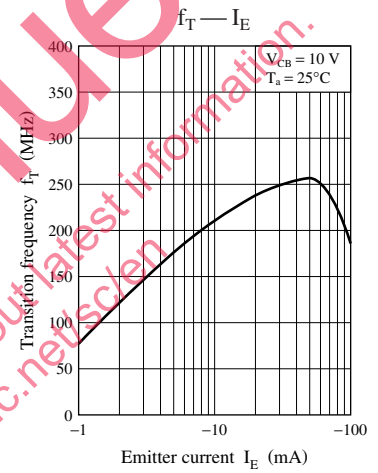
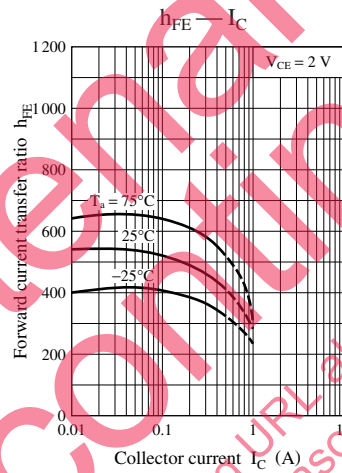
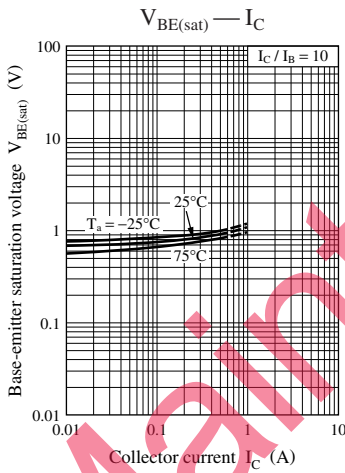
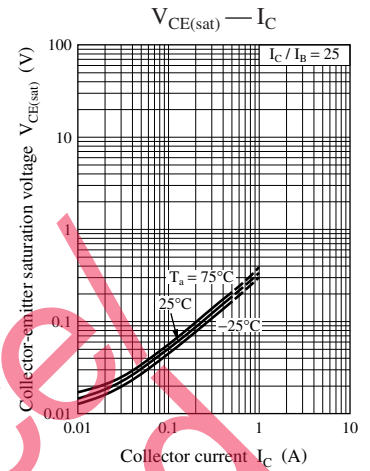
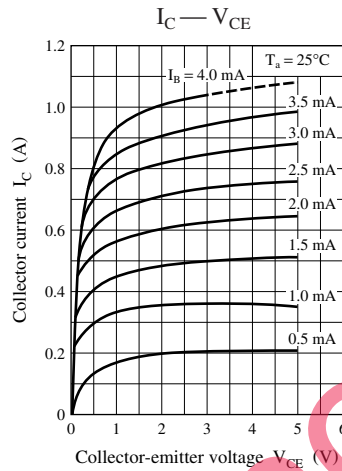
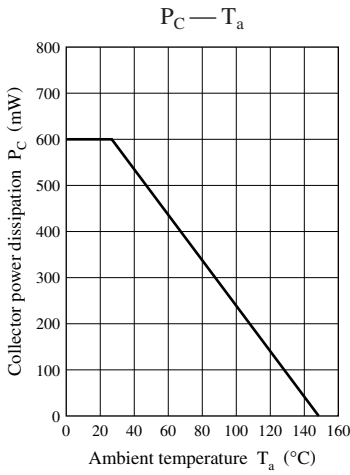
2. \*1: Pulse measurement

\*2: Rank classification

| Rank      | R          | S          | T          |
|-----------|------------|------------|------------|
| $h_{FE1}$ | 200 to 350 | 300 to 500 | 400 to 800 |

\*3:  $R_{on}$  Measurement circuit





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